
Materials and Processes for Semiconductor, 2.5 and 3D Chip Packaging and High Density Interconnection PCB 2

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Table of Contents

<i>Preface</i>	<i>iii</i>
<i>(Invited)</i> 3D Passive Devices and Through-Substrate Connections for Medical and Automotive Applications <i>C. Bunel, E. Lefeuvre, S. Jacqueline, M. Jatlaoui</i>	1
Line Width and Capping Layer Effects on Electromigration Failure of Plasma Etched Copper Lines <i>M. Li, J. Q. Su, Y. Kuo</i>	9
Model Identification for Adsorption Dynamics and Suppression Effect of Polyethylene Glycol Using Inverse Analysis Approach <i>T. Ishii, K. Amaya, Y. Onishi</i>	17
<i>(Invited)</i> Application of Three Dimensional Chip Stacking Technology for Fully Depleted Silicon-on-Insulator Quantum Beam Imager <i>I. Kurachi, T. Tsuboyama, Y. Arai, M. Motoyoshi</i>	29
Molybdenum Capping Layer Effect on Electromigration Failure of Plasma Etched Copper Lines <i>J. Q. Su, M. Li, Y. Kuo, S. Hamaguchi</i>	39
Author Index	47